PCN Number:	nber: 20180102000 PCN Date: Feb. 12, 2						12, 2018			
Title: .3 720p S245 TRP DMD Process Change and DLPC34xx Controller Software/Firmware Change								nware		
Customer Contact:	DLP-PCN-	Team@lis			Dept:	D	DLP CQE			
Proposed 1 st Ship Date:	18	Estimated Sample Availability:			F	Feb. 12, 2018				
Change Type:										
Assembly S	Site		Design				Wafer Bum	Site		
Assembly F	rocess		Data She	heet			Wafer Bum	er Bump Material		
Assembly N			Part num	nber change			Wafer Bump Process			
Mechanical Specification			Software /Firmware				Wafer Fab 9	Site		
Packing/Sh	Packing/Shipping/Labeling		Test Process				Wafer Fab Materials			
							Wafer Fab Process			
PCN Details										
Description of Change:										
 Texas Instruments Incorporated is announcing the change of a proprietary material used in the DMD process as well as a part number change for all Pico TRP affected devices. TI plans to obsolete the existing part numbers for all Pico TRP affected devices. This will be communicated officially through an end-of-life PCN at a later date. The new process DMDs have mandatory software (SW) requirements. Detailed information can be found in the following Application Note on the extranet. Software Requirements for TI DLP® Pico™ TRP Digital Micromirror Devices Embedded SW is backward compatible with existing devices. TI encourages customers to transition to new SW immediately when it becomes available. Consult your application engineer for questions or if you need access to TI's mySecure Software site. 										
Reason for Ch		roactive ch	omical us	o policy	and conti	n i.t	v of cupply			
This change is p	•							/ nogat	hively	
Anticipated in	ipact on For	III, FIL, F	unction, C	Zuanty	or Kellab	HILL	y (positive)	negat	ive):	
None										
Anticipated in										
No Impac Material Declarati	produ relea obtai mate	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the <u>TI Eco-Info website</u> . There is no impact to the material meeting current regulatory compliance requirements with this PCN change.								
Changes to product identification resulting from this PCN:										
Device	Orderable P/N	e New	Orderable P/N		SW lability* [*]	ķ	DMD Samples	DM	D MP	
.3 720p S245	S245 7212-313BK		7212-323BK A		lable now		Available Available		ble now	
.3 720p S245	.3 720p S245 DLP3010FQK DLP30		8010AFQK	AFQK Available no			Available now	Available now		
	ontroller C34xx	Softv Firm	ginal vare / ware 04.12.07	S	w Processoftware		SW Availabil			

Qualification Data

This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Product Applications:

See the DMD device sheet and Application Note "<u>Software Requirements for TI DLP® Pico™ TRP Digital Micromirror Devices</u>" for application details.

<u>.3 720p S245 TRP Device</u> Part# (7212-323BK, DLP3010AFQK)

Qualification Tests & Results:

The .3 720p S245 TRP Device Qualification has passed. The following life, environmental, and inspection tests were conducted as per the approved qualification plan and test requirements. Details are mentioned below.

Test	Conditions	Quantity	Results	
A. Life Test: *				
High Temp Operating Life	95°C, 500hr or equivalent	40	Pass	
Nominal Operating Life w/o Precondition	70°C, 670hr or equivalent	40	Pass	
Preconditioning + Nominal Operating Life:				
(a) Precondition	UBH 110°C/85%RH, 500hr	40	Pass	
(b) Nominal Operating Life	70°C, 670hr or equivalent			
Low Temp Operating Life	-10°C, 500hr or equivalent	40	Pass	
Projector Life w/o Precondition	Ambient Temperature, 1000hr or equivalent	9	Pass	
Preconditioning + Projector Life	1000iii oi equivarent			
(a) Precondition	UBH 110°C/85%RH, 500hr			
,	Ambient Temperature,	9	Pass	
(b) Projector Life	500hr or equivalent			
B. Environmental Tests: *				
High Temp Storage Life	125°C, 500hr or equivalent	30	Pass	
Temperature Cycling	0°C/+100°C 1000cycles	77	Pass	
Unbiased HAST	UBH 110°C/85%RH, 500hr	27	Pass	
ESD	RT, HBM per Data Sheet	9	Pass	
Latch Up	RT, +/-100mA	9	Pass	
Mechanical Stress Sequence	III, IJ 100IIIA	3	1 033	
(a) Electrical Test				
(b) Mechanical Shock	1500g, 0.5ms, 6axis, 5 pulses	32	Pass	
(c) Vibration	20g, 20-2000Hz, All planes (x, y, z)			
(d) Acceleration	10Kg, Y1 plane only			
(e) Electrical Test				
Thermal Stress Sequence				
(a) Electrical Test				
(b) Thermal Shock	0°C/+100°C, 15 cycles		Descri	
(c) Temp. Cycle	0°C/+100°C, 100 cycles	32	Pass	
(d) Moisture Resistance	10 days			
(a) Electrical Test				
C. Inspection Tests:				
Physical Dimensions		10	Pass	
Internal Water Vapor		10	Pass	
Window Pull		10	Pass	
Bond Strength		9	Pass	
D. Others:				
Image Quality		30	Pass	
Optical Performance		30	Pass	

 $[\]hbox{* Any conditions beyond the Recommended Operating Conditions listed in the Datasheet are run at accelerated test conditions.}$

For questions regarding this notice, emails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com